FIG. 1

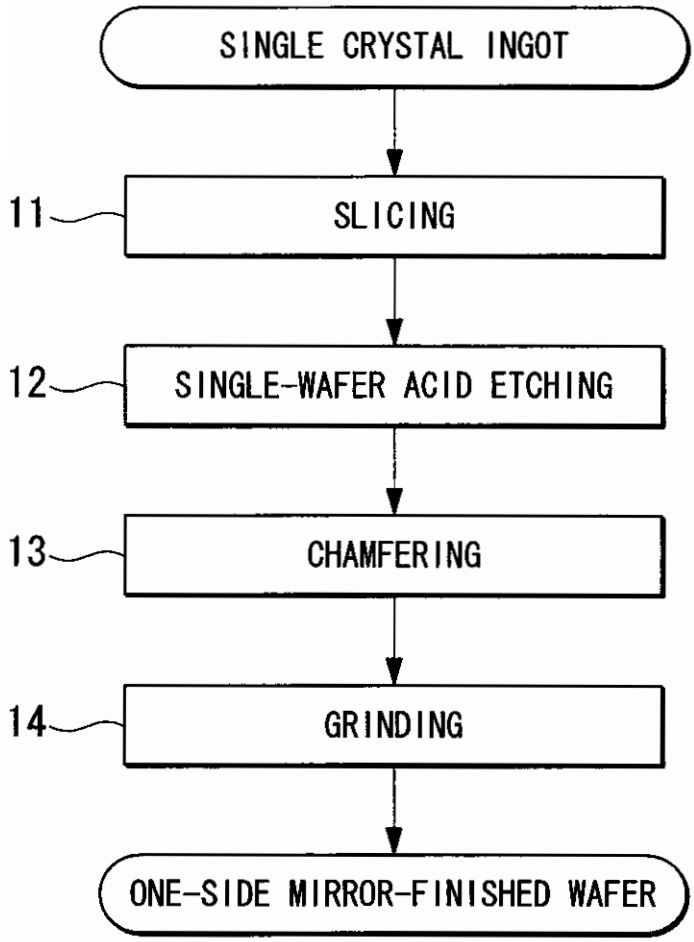

SINGLE CRYSTAL INGOT
11
SLICING
12
SINGLE-WAFER ACID ETCHING
13
CHAMFERING
14
GRINDING
ONE-SIDE MIRROR-FINISHED WAFER

FIG. 2

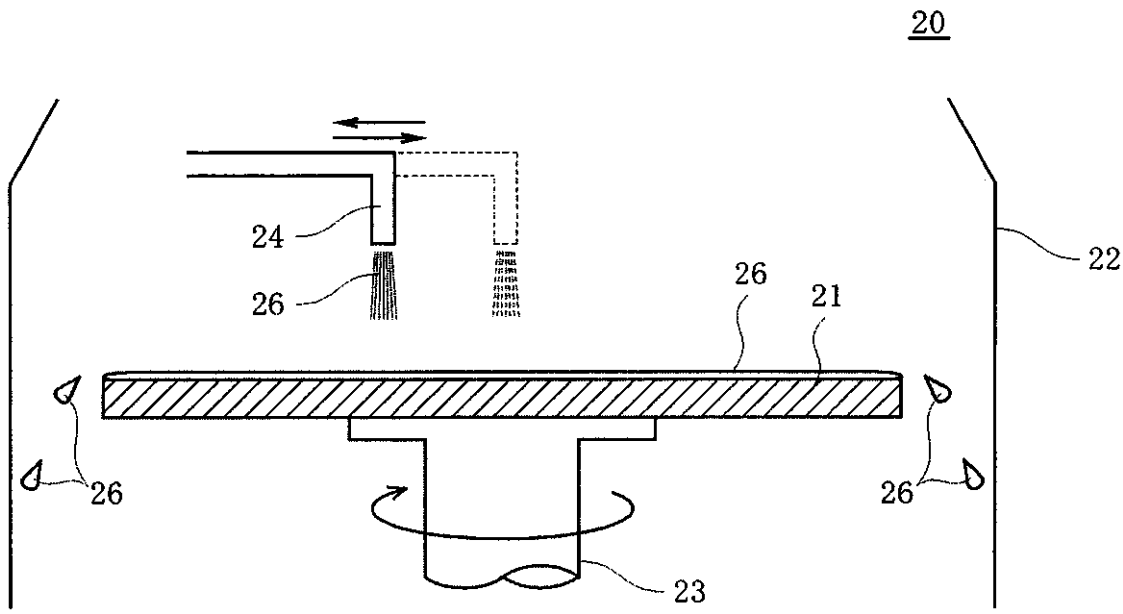


FIG. 3

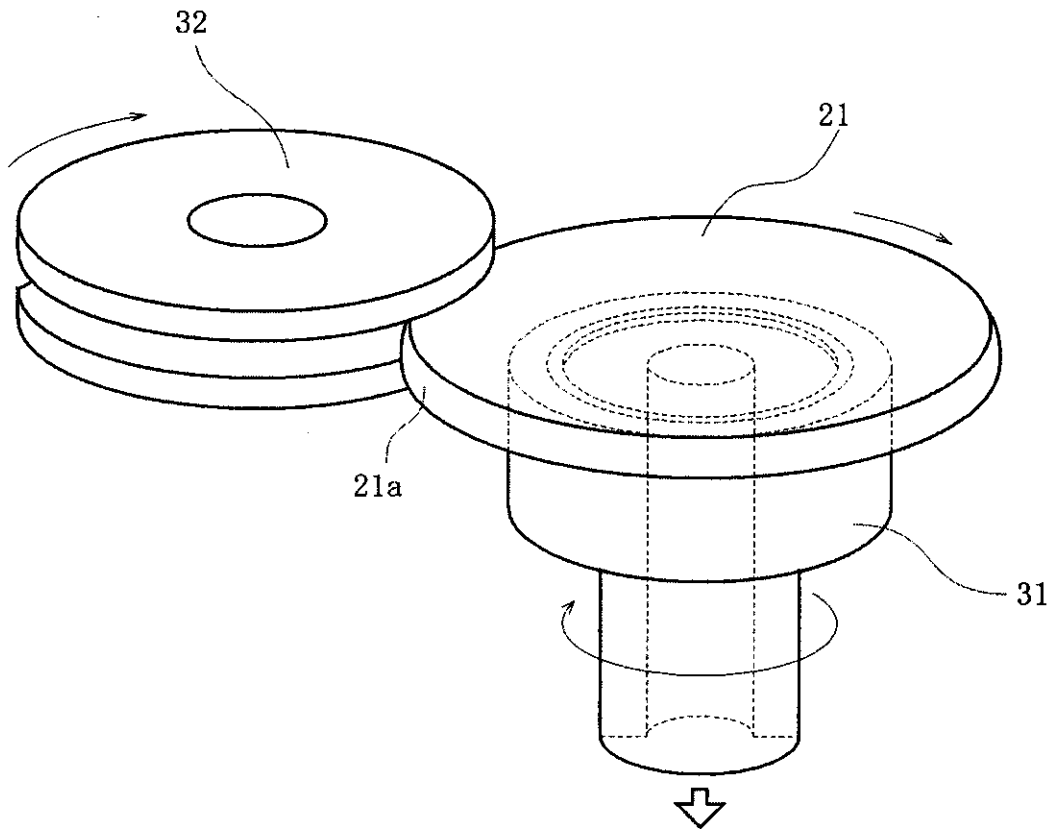


FIG. 4

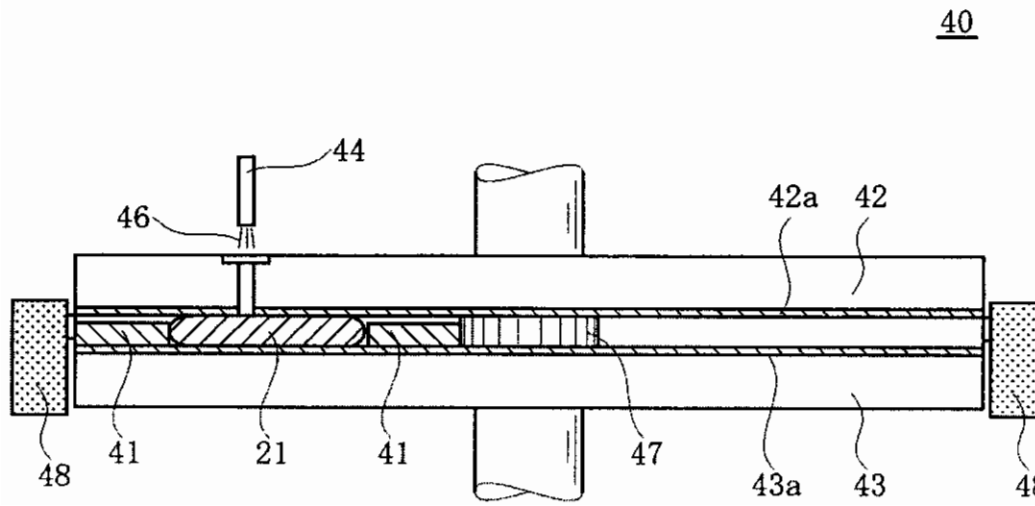
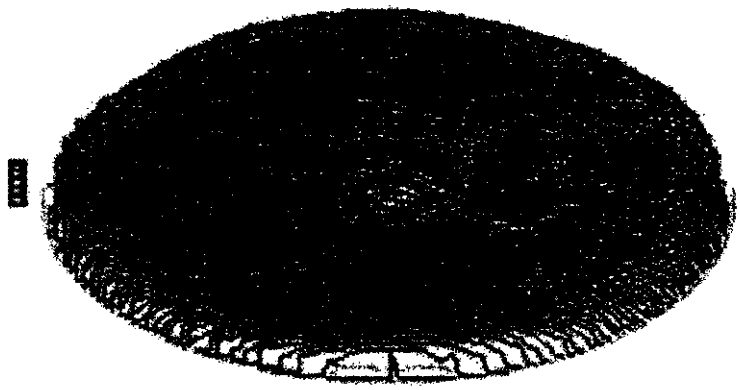


FIG. 5



1div : 3.0 μ m
Full Scale : 15.0 μ m

FIG. 6



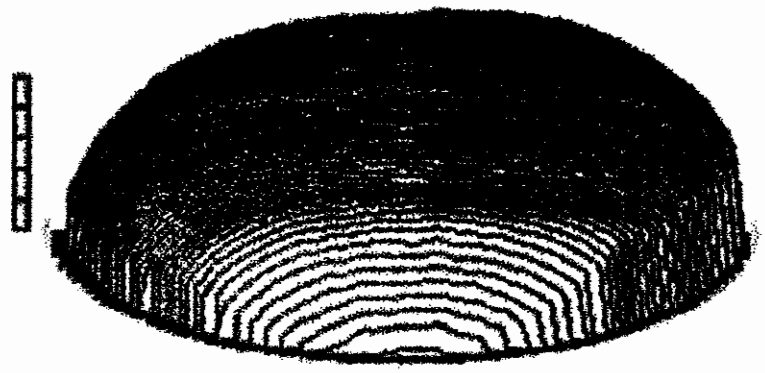
1div : 1.0 μ m
Full Scale : 5.0 μ m

FIG. 7



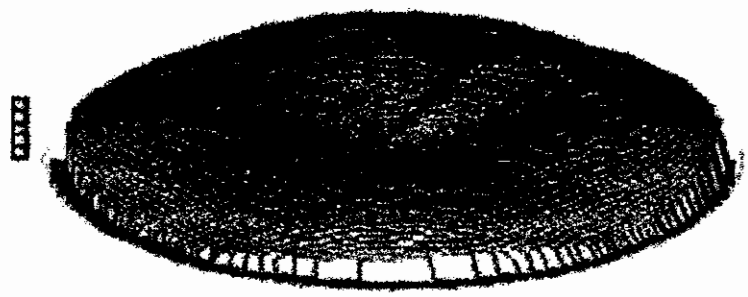
1div : 0.05 μ m
Full Scale : 0.25 μ m

FIG. 8



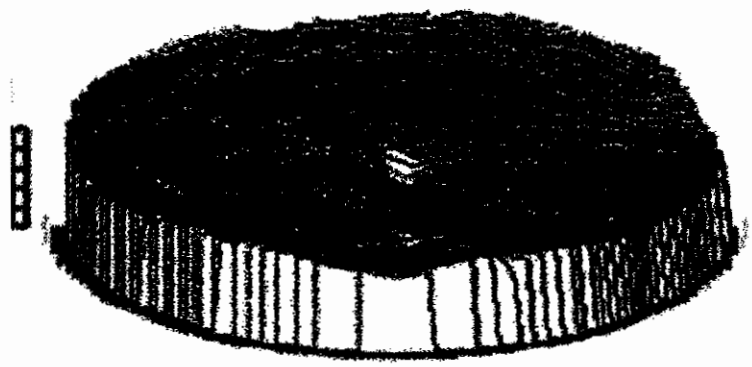
1div : 3.0 μ m
Full Scale : 15.0 μ m

FIG. 9



1div : 1.0 μ m
Full Scale : 5.0 μ m

FIG. 10



1div : 0.5 μ m
Full Scale : 2.5 μ m

FIG. 11



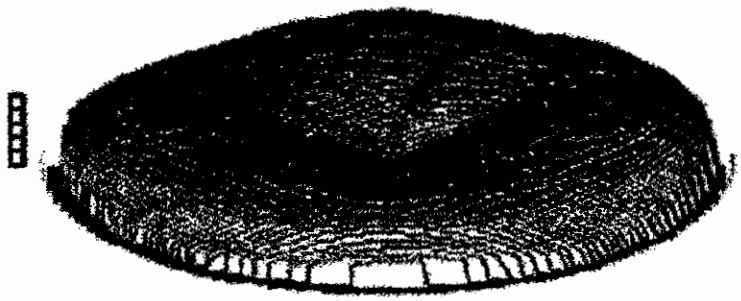
1div : 0.05 μ m
Full Scale : 0.25 μ m

FIG. 12



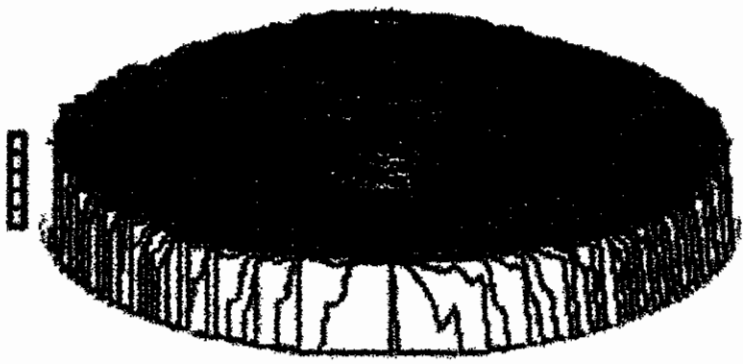
1div : 3.0 μ m
Full Scale : 15.0 μ m

FIG. 13



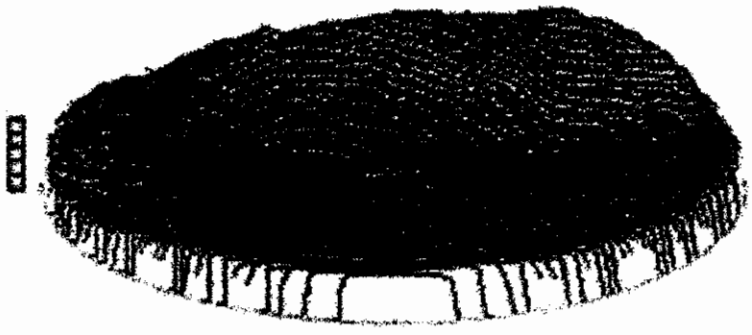
1div : 1.0 μ m
Full Scale : 5.0 μ m

FIG. 14



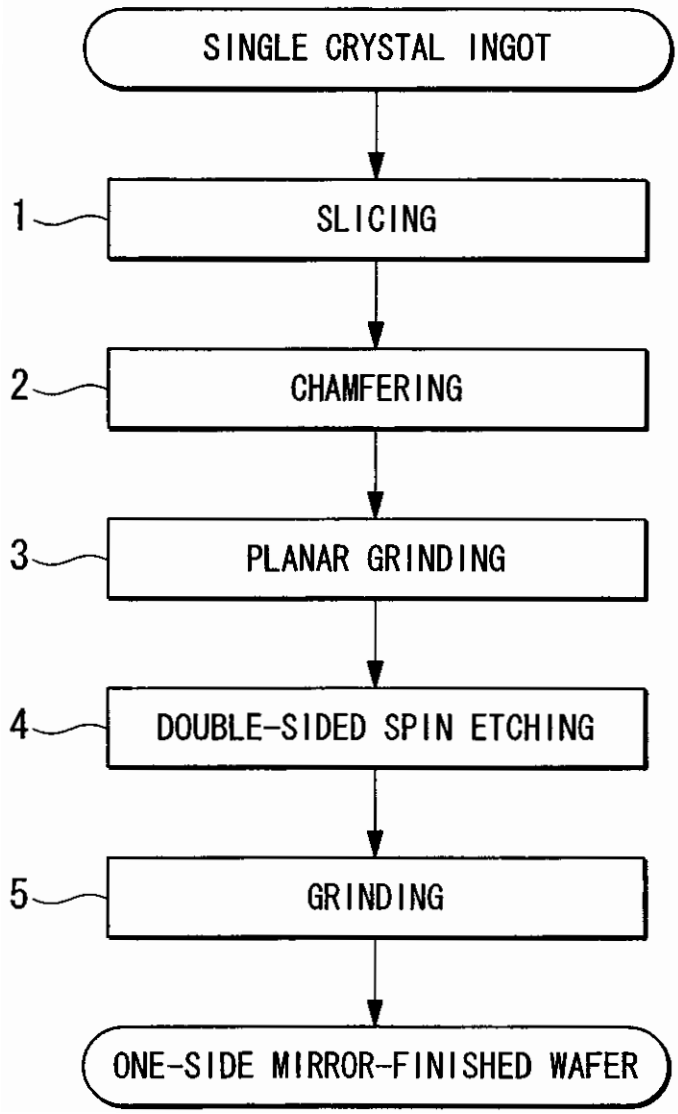
1div : 0.5 μ m
Full Scale : 2.5 μ m

FIG. 15



1div : 0.05 μ m
Full Scale : 0.25 μ m

FIG. 16


SINGLE CRYSTAL INGOT
1
SLICING
2
CHAMFERING
3
PLANAR GRINDING
4
DOUBLE-SIDED SPIN ETCHING
5
GRINDING
ONE-SIDE MIRROR-FINISHED WAFER